



UNIVERSITÀ
DEGLI STUDI DI TRIESTE



Template List for SVT Fanouts

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Summary

- First contacts with Erik Vallazza (CERN, Mipot)
- BaBar experience (unfortunately not mine)
- I've started writing Latex Template
 - Adding Layer0 (see Stefano presentation)
 - Layer 1-5 as BaBar with the extended geometry
 - Numbers will still be very rough (I can assume same number of Φ strips and 45% more Z strips)
 - Prototypes and possible improvements: needed for Layer0, probably not needed for Layer 1-5

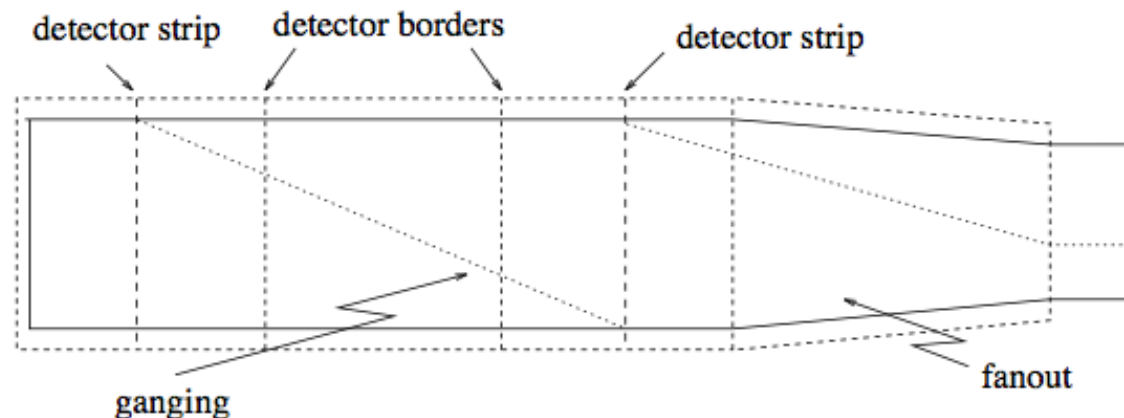
Some Final Fanout parameters from BaBar

Biblio: TDR, BaBar Notes 376 (Fanout specs), 307 (Assembly), 312 (Final Geom), 273 (Numbering Conventions), 306, 392, BaBar detector.

- 50 μm thick Upilex substrate
- 4.5 μm Cu layer deposited on 150 nm layer of adhesive Cr
- <1 μm Au layer on another 150 nm layer of Cr
- Average rad. length $0.03\%X_0$
- $R=1.6 \Omega/\text{cm}$ $R_{IS}>2\text{M}\Omega$
- $C_{IS}=0.52\text{pF}/\text{cm}$

Some Fanout parameters from BaBar (cont.)

- 28 different designs to accommodate all layer specs: 01 02 03 4A 4B 5A 5B; Forw Backw; Z Phi.
- Total 208 fanouts for the 6 6 6 16 18 modules
- Minimum pitch 41 μm (on wafer type VI Wedge)
- Line width depends on strip pitch, 30(70) μm on 100 (210) μm strip pitch, reducing to 20 μm on electronics side (min. 8 μm)
- 2x Ganging on Layers Z 4 & 5 (from 55% to 98.9 %)



Production and Quality Control Procedures

- Design @ Trieste (PCAD including test structures)
- CERN production and first visual inspection (to check for opens and to remove shorts)
- Trieste (~~Della Ricca~~, Lanceri, ~~Pontoni~~, ~~Poropat~~, ~~Prest?~~, Vallazza) + (tecn. Bari, Benedetti) more accurate tests, shorts removal, cut test structures and second test after cut (150 working days)
- Accepted only 3 lost strips (<0.55%) and 0 shorts (90% yield on Φ and 70% on Z)

Table

I can starting updating
this table (that is
not the final one)

Layer	Fanout Type	Length (cm)	Number of Readout		Typical Pitch at		Number of Circuits
			Strips	Channels	Input (μm)	Output (μm)	
1	z , F+B	12.5	950	768	100	50	12
	ϕ , F+B	3.0	768	768	50	50	12
2	z , F+B	14.5	1150	1024	100	50	12
	ϕ , F+B	3.0	960	1024	50	50	12
3	z , F+B	15.6	1360	1280	100	50	12
	ϕ , F+B	2.0	1280	1280	50	50	12
4a	z , F	19.7	885	512	200	50	8
	z , B	24.3	1115	512	200	50	8
	ϕ , F+B	2.0	512	512	65	50	16
4b	z , F	20.6	930	512	200	50	8
	z , B	24.2	1160	512	200	50	8
	ϕ , F+B	2.0	512	512	65	50	16
5a	z , F	25.2	1160	512	200	50	9
	z , B	25.1	1205	512	200	50	9
	ϕ , F+B	2.0	512	512	65	50	18
5b	z , F+B	26.1	1205	512	200	50	18
	ϕ , F+B	2.0	512	512	65	50	18

Table 4-5. Summary of fanout circuit characteristics.

Latex template

- Separate description for Layer 0 and Layer1-5
- Paragraphs:
 - Description and Requirements
 - Specs (typical R,C,X₀)
 - Design
 - Table with Types, #pieces, #lines, %ganging
(Final depends on wafers size, pitch, #readout strips, #chips)
 - Fabrication
 - Quality Control Procedures
 - Need to put a final paragraph on R&D, Prototypes, Optimization, Improvements? (for layer0 yes)

Backup

Final BaBar Tables

Layer	#wafers/fwd mod	#wafers/bkwd mod	phi pitch(μm)	z pitch (μm)
1	2	2	50	100
2	2	2	55	100
3	3	3	55	100
4a	3	4	100	210
4b	3	4	100	210
5a	4	4	100	210
5b	4	4	100	210

Wafer type	I	II	III	IV	V	VI (wedge)
Dimensions (mm)						
z	42.40	45.40	43.90	67.55	53.9	67.97
phi	41.30	49.415	71.47	52.50	52.50	52.80 $\rightarrow$ 43.30
Readout pitch (μm)						
z	100	100	100	210	210	210
phi	50	55	55	100	100	100 $\rightarrow$ 82
Number of strips						
z	411	441	426	316	251	318
phi	799	874	1275	512	512	512

From
BaBar Note 273

Layer	#chips/readout section	# r/o channels	# phi r/o strips	# z r/o strips (f/b)
1	7	896	799	822
2	7	896	874	882
3	10	1280	1275	1278
4a	5	640	512	885/1071
4b	5	640	512	950/1071
5a	5	640	512	1201/1266
5b	5	640	512	1266/1266

Wafer type	I	II	III	IV	V	VI (wedge)
Dimensions (mm)						
z (L)	42.40	45.40	43.90	67.55	53.9	67.97
ϕ (W)	41.30	49.415	71.47	52.50	52.50	52.80 $\rightarrow$ 43.30
Readout pitch (μm)						
z	100	100	100	210	210	210
ϕ	50	55	55	100	100	100 $\rightarrow$ 82
Number of readout strips						
z	411	441	426	316	251	318
ϕ	799	874	1275	512	512	512
Phys. strip pitch (μm)						
z	50	50	50	105	105	105
ϕ	50	55	55	50	50	50 $\rightarrow$ 41

From
BaBar Note 312
& 307

Quantity	Layer 1	Layer 2	Layer 3	Layer 4a	Layer 4b	Layer 5a	Layer 5b
Radius (mm)	32	40	54	124	127	140	144
Wafers/Module	4	4	6	7	7	8	8
Modules/Layer	6	6	6	8	8	9	9
R.O. Sections/Module	4	4	4	4		4	
ICs/R.O. Section	7	7	10	5		5	
Strip Length, b/f (mm):							
ϕ	82	88	127	230/189	230/203	270/257	270/270
z	40	48	70	42-51	42-51	42-51	42-51
z Ganging (f/b):				34%/67%	48%/67%	88%/98%	98%/98%
Readout pitch (μm):							
ϕ	50	55	55	80-100		80-100	
z	100	100	100	210		210	
Floating Strips:							
ϕ	—	—	—	1		1	
z	1	1	1	1		1	
Intrinsic Resolution(μm):							
ϕ	10	10	10	10-12		10-12	
z	12	12	12	25		25	

From
BaBar Note 306